



Material Content Data Sheet



Sales Product Name	BTF6070-2EKV			Issued		26. August 2019		
MA#	MA005398904							
Package	PG-DSO-14-40			Weight*		149.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.675	1.79	1.79	17919	17919
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		117	
	non noble metal	zinc	7440-66-6	0.070	0.05		466	
	non noble metal	iron	7439-89-6	1.392	0.93		9323	
	non noble metal	copper	7440-50-8	56.512	37.86	38.85	378569	388475
wire	non noble metal	copper	7440-50-8	0.424	0.28	0.28	2838	2838
encapsulation	organic material	carbon black	1333-86-4	0.169	0.11		1135	
	plastics	epoxy resin	-	7.791	5.22		52193	
	inorganic material	silicondioxide	60676-86-0	76.726	51.41	56.74	513984	567312
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8214	8214
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9496	9496
glue	plastics	epoxy resin	-	0.150	0.10		1006	
	noble metal	silver	7440-22-4	0.708	0.47	0.57	4740	5746
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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